

N-Channel Enhancement Mode Field Effect Transistor

Common Drain, ESD Protection

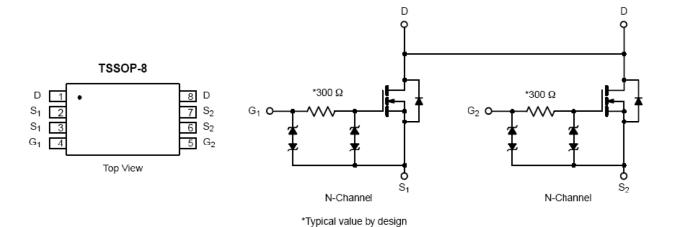
FEATURES

- Super high dense cell design for low RDS(ON)
- Rugged and reliable
- Simple drive requirement
- TSSOP-8 package

PRODUCT SUMMARY					
V _{DSS}	lσ	R _{DS(ON)} (mΩ) Typ			
20V	6.5A	18@ V _{GS} =4.5V			
200	0.5A	23 @ V _{GS} =2.5V			
ESD Protected: 3000 V					



NOTE: The MT6968 is available in a lead-free package



ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise noted)

Parameter	Symbol	MOSFET	Units
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	Vgs	±12	V
Continuous Drain Current ^A	lo	6.5	А
Pulsed Drain Current ^B	Ірм	30	А
Continuous Source Current (Diode Conduction)a	Is	1.5	А
Power Dissipation	PD	1.5	W
Junction and Storage Temperature Range	Tı, Tsтg	-55 to 150	$^{\circ}$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to Ambient ^a Rth J _A 70 °C/W	Thermal Resistance, Junction-to Ambient ^a	Rth JA	70	°C/W
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ELECTRICAL CHARACTERISTICS (Ta=25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS					1	I
Drain-Source Breakdown Voltage	BVDSS	Vgs=0V,Ip=-250μA	20			V
Zero Gate Voltage Drain Current	IDSS	VDS=-16V,VGS=0V			1	μΑ
Gate-Body Leakage	lgss	Vgs=±8V,Vps=0V			±200	nA
ON CHARACTERITICS						
Gate Threshold Voltage	Vgs(th)	VDS=VGS,ID=-250μA	0.8	1.0	1.2	V
Drain-Source On-State Resistance	Descrip	Vgs=4.5V,ID=6.5A		18	23	- mΩ
	RDS(ON)	Vgs=2.5V,ID=5.5A		23	28	
Forward Transconductance	grs	VGS=5V,ID=6.5A		30		S
DAYNAMIC CHARACTERISTICS			•		•	
Input Capacitance	Ciss	V _{DS} =-10V,V _{GS} =0V f=1.0MHz		540		рF
Output Capacitance	Coss			72		pF
Reverse Transfer Capacitance	Crss			49		pF
SWITCHING CHARACTERISISTICS			1		1	
Turn-On Delay Time	t _D (ON)	VDD=10V ID=1A, VGEN=4.5V RL=10ohm RGEN=6ohm		245		ns
Rise Time	tr			330		ns
Turn-Off Delay Time	t _{D(OFF)}			860		ns
Fall Time	tf			510		ns
Total Gate Charge	Qg	VDS=10V,ID=6.5A VGS=4.5V		12	18	nC
Gate-Source Charge	Qgs			2.2		nC
Gate-Drain Charge	Qgd			3.6		nC



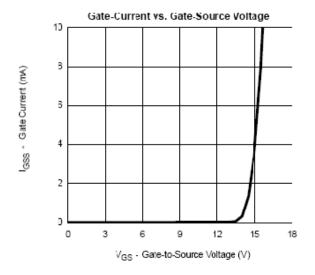
ELECTRICAL CHARACTERICS (TA=25 ℃ unless otherwise noted)

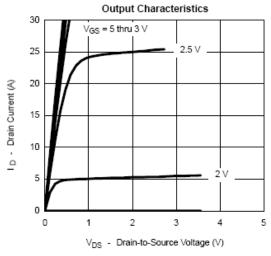
Parameter	Symbol	Condition	Min	Тур	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage	Vsd	Vgs=0V,Is=1.5A		0.71	1.2	V

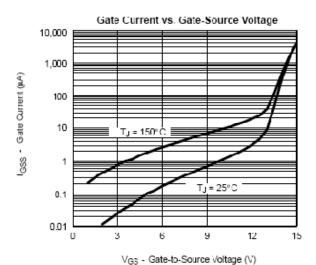
Notes

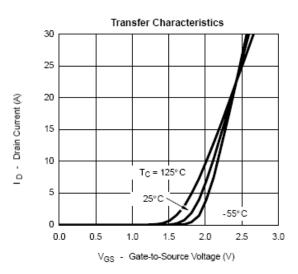
- a. Surface Mounted on FR4 Board, t ≤ 10sec
- b. Pulse Test: Pulse Width ≤ 300Us, Duty Cycle ≤ 2%
- c. Guaranteed by design, not subject to production testing.

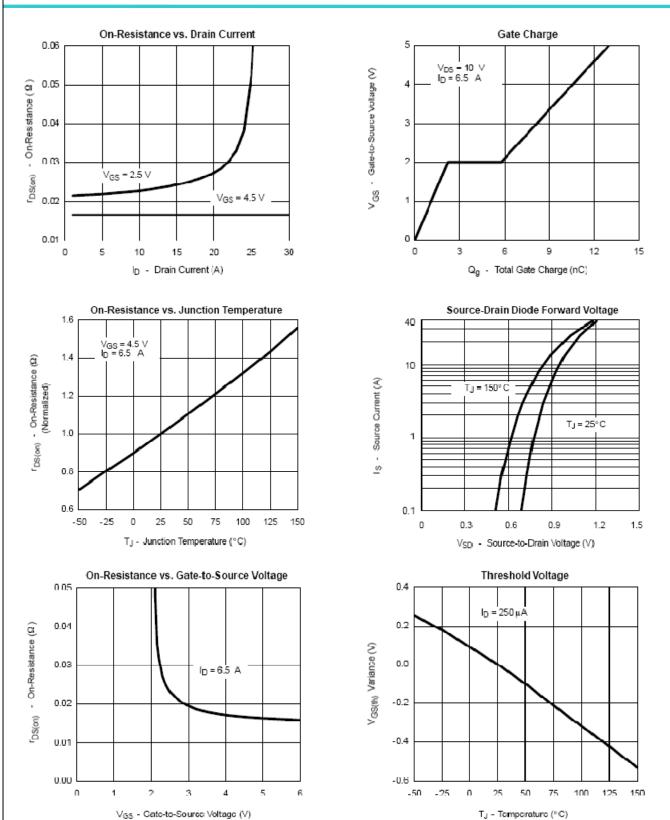
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

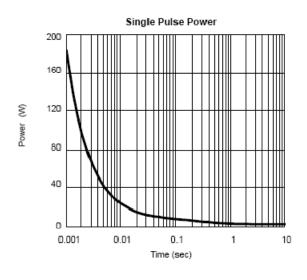


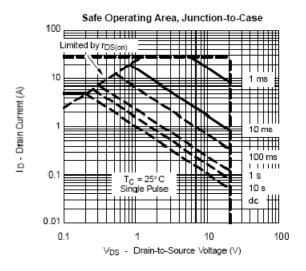


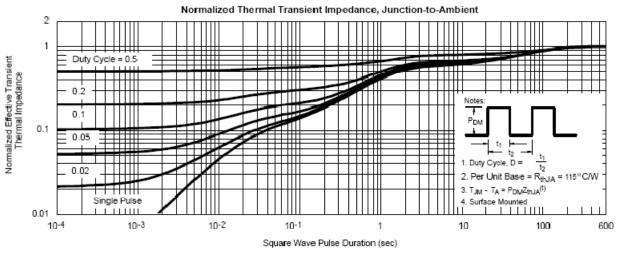


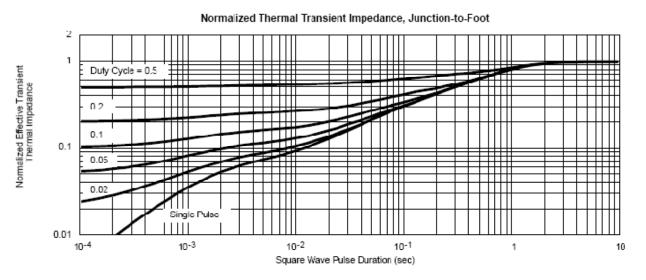












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